FORM PTO-1449 (Modified for Citation of Foreign Cited References)	ATTY. DOCKET NO.	SERIAL NO.
LIST OF INFORMATION PROVIDED BY APPLICANT	USA.02.022	10/091086
(Use several sheets if necessary)	APPLICANT: STEWART, et al	
	FILING DATE: March 5, 2002	GROUP: Unknown

REFERENCE DESIGNATION — U.S. PATENT DOCUMENTS

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EXAMINER: Thien Tran — DATE CONSIDERED: 09/08/04

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INFORMATION DISCLOSURE STATEMENT BY APPLICANT

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Sheet 1 of 2

Complete if Known	
Application Number	10/091, 086
Filing Date	03/05/2002
First Named Inventor	Stewart, Steven L.
Art Unit	
Examiner Name	
Attorney Docket Number	US.01.012

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Examiner Initials*	Cite No.[1]	Document Number Number-Kind Code[2] (if known)	Publication Date MM-DD-YYYY	Name of Patentee or Applicant of Cited Document	Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear
TT		US- 4873397	10-10-1989	Masujima et al	
TT		US- 6037657	03-14-2000	Tsurumi et al	
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Examiner Initials*	Cite No.[1]	Foreign Patent Document Country Code[3]-Number[4]-Kind Code[5] (if known)	Publication Date MM-DD-YYYY	Name of Patentee or Applicant of Cited Document	Pages, Columns, Lines, Where Relevant Passages Or Relevant Figures Appear	T[6]
TT		EP 0729182A	08-28-1996	Matsushita Electric Inc		
TT		DE 19822470A	12-09-1999	Litton Precision Product		
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Examiner Signature		Date Considered	09/08/04

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INFORMATION DISCLOSURE STATEMENT BY APPLICANT

(Use as many sheets as necessary)

Sheet 2 of 2

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Application Number	10/091,086
Filing Date	03/05/2002
First Named Inventor	Stewart, Steven L.
Art Unit	
Examiner Name	
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